



## Phase Control Thyristors (Hockey PUK Version), 500 A



A-PUK (TO-200AB)

### FEATURES

- Center amplifying gate
- Metal case with ceramic insulator
- International standard case A-PUK (TO-200AB))
- Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

RoHS  
COMPLIANT

### TYPICAL APPLICATIONS

- DC motor controls
- Controlled DC power supplies
- AC controllers

### PRIMARY CHARACTERISTICS

$I_{T(AV)}$	500 A
$V_{DRM}/V_{RRM}$	400 V, 600 V
$V_{TM}$	1.36 V
$I_{GT}$	90 mA
$T_J$	-40 °C to +125 °C
Package	A-PUK (TO-200AB)
Circuit configuration	Single SCR

### MAJOR RATINGS AND CHARACTERISTICS

PARAMETER	TEST CONDITIONS	VALUES	UNITS
$I_{T(AV)}$		500	A
	$T_{hs}$	55	°C
$I_{T(RMS)}$		960	A
	$T_{hs}$	25	°C
$I_{TSM}$	50 Hz	7850	A
	60 Hz	8220	
$I^2t$	50 Hz	308	kA <sup>2</sup> s
	60 Hz	281	
$V_{DRM}/V_{RRM}$		400 to 600	V
$t_q$	Typical	100	µs
$T_J$		- 40 to 125	°C

### ELECTRICAL SPECIFICATIONS

#### VOLTAGE RATINGS

TYPE NUMBER	VOLTAGE CODE	$V_{DRM}/V_{RRM}$ , MAXIMUM REPETITIVE PEAK AND OFF-STATE VOLTAGE V	$V_{RSM}$ , MAXIMUM NON-REPETITIVE PEAK VOLTAGE V	$I_{DRM}/I_{RRM}$ MAXIMUM AT $T_J = T_J$ MAXIMUM mA
ST280C..C	04	400	500	30
	06	600	700	

**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average on-state current at heatsink temperature	$I_{T(AV)}$	180° conduction, half sine wave double side(single side) cooled		500 (185)	A
				55 (85)	°C
Maximum RMS on-state current	$I_{T(RMS)}$	DC at 25 °C heatsink temperature double side cooled		960	
Maximum peak, one-cycle non-repetitive surge current	$I_{TSM}$	t = 10 ms	No voltage reapplied	7850	A
		t = 8.3 ms	No voltage reapplied	8220	
		t = 10 ms	100 % $V_{RRM}$ reapplied	6600	
		t = 8.3 ms	100 % $V_{RRM}$ reapplied	6900	
Maximum $I^2t$ for fusing	$I^2t$	t = 10 ms	No voltage reapplied	308	kA <sup>2</sup> s
		t = 8.3 ms	No voltage reapplied	281	
		t = 10 ms	100 % $V_{RRM}$ reapplied	218	
		t = 8.3 ms	100 % $V_{RRM}$ reapplied	200	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	t = 0.1 to 10 ms, no voltage reapplied		3080	kA <sup>2</sup> √s
Low level value of threshold voltage	$V_{T(TO)1}$	$(16.7 \% \times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)})$ , $T_J = T_J$ maximum		0.84	V
High level value of threshold voltage	$V_{T(TO)2}$	$(I > \pi \times I_{T(AV)})$ , $T_J = T_J$ maximum		0.88	
Low level value of on-state slope resistance	$r_{t1}$	$(16.7 \% \times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)})$ , $T_J = T_J$ maximum		0.50	mΩ
High level value of on-state slope resistance	$r_{t2}$	$(I > \pi \times I_{T(AV)})$ , $T_J = T_J$ maximum		0.47	
Maximum on-state voltage	$V_{TM}$	$I_{pk} = 1050$ A, $T_J = 125$ °C, $t_p = 10$ ms sine pulse		1.36	V
Maximum holding current	$I_H$	$T_J = 25$ °C, anode supply 12 V resistive load		600	mA
Maximum (typical) latching current	$I_L$			1000 (300)	

**SWITCHING**

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum non-repetitive rate of rise of turned-on current	$di/dt$	Gate drive 20 V, 20 Ω, $t_r \leq 1$ μs $T_J = T_J$ maximum, anode voltage $\leq 80$ % $V_{DRM}$	1000	A/μs
Typical delay time	$t_d$	Gate current 1 A, $di_g/dt = 1$ A/μs $V_d = 0.67$ % $V_{DRM}$ , $T_J = 25$ °C	1.0	μs
Typical turn-off time	$t_q$	$I_{TM} = 300$ A, $T_J = T_J$ maximum, $di/dt = 20$ A/μs, $V_R = 50$ V, $dV/dt = 20$ V/μs, gate 0 V 100 Ω, $t_p = 500$ μs	100	

**BLOCKING**

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum critical rate of rise of off-state voltage	$dV/dt$	$T_J = T_J$ maximum linear to 80 % rated $V_{DRM}$	500	V/μs
Maximum peak reverse and off-state leakage current	$I_{RRM}$ , $I_{DRM}$	$T_J = T_J$ maximum, rated $V_{DRM}/V_{RRM}$ applied	30	mA



TRIGGERING						
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES		UNITS
				TYP.	MAX.	
Maximum peak gate power	P <sub>GM</sub>	T <sub>J</sub> = T <sub>J</sub> maximum, t <sub>p</sub> ≤ 5 ms		10.0		W
Maximum average gate power	P <sub>G(AV)</sub>	T <sub>J</sub> = T <sub>J</sub> maximum, f = 50 Hz, d% = 50		2.0		
Maximum peak positive gate current	I <sub>GM</sub>	T <sub>J</sub> = T <sub>J</sub> maximum, t <sub>p</sub> ≤ 5 ms		3.0		A
Maximum peak positive gate voltage	+ V <sub>GM</sub>	T <sub>J</sub> = T <sub>J</sub> maximum, t <sub>p</sub> ≤ 5 ms		20		V
Maximum peak negative gate voltage	- V <sub>GM</sub>			5.0		
DC gate current required to trigger	I <sub>GT</sub>	T <sub>J</sub> = - 40 °C	Maximum required gate trigger/ current/voltage are the lowest value which will trigger all units 12 V anode to cathode applied	180	-	mA
		T <sub>J</sub> = 25 °C		90	150	
		T <sub>J</sub> = 125 °C		40	-	
DC gate voltage required to trigger	V <sub>GT</sub>	T <sub>J</sub> = - 40 °C		2.9	-	V
		T <sub>J</sub> = 25 °C		1.8	3.0	
		T <sub>J</sub> = 125 °C		1.2	-	
DC gate current not to trigger	I <sub>GD</sub>	T <sub>J</sub> = T <sub>J</sub> maximum	Maximum gate current/voltage not to trigger is the maximum value which will not trigger any unit with rated V <sub>DRM</sub> anode to cathode applied	10		mA
DC gate voltage not to trigger	V <sub>GD</sub>			0.30		

THERMAL AND MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum operating junction temperature range	$T_J$			- 40 to 125	°C
Maximum storage temperature range	$T_{Stg}$			- 40 to 150	
Maximum thermal resistance, junction to heatsink	$R_{thJ-hs}$	DC operation single side cooled		0.17	K/W
		DC operation double side cooled		0.08	
Maximum thermal resistance, case to heatsink	$R_{thC-hs}$	DC operation single side cooled		0.033	
		DC operation double side cooled		0.017	
Mounting force, $\pm 10$ %				4900 (500)	N (kg)
Approximate weight				50	g
Case style		See dimensions - link at the end of datasheet		A-PUK (TO-200AB)	

$\Delta R_{thJC}$ CONDUCTION						
CONDUCTION ANGLE	SINUSOIDAL CONDUCTION		RECTANGULAR CONDUCTION		TEST CONDITIONS	UNITS
	SINGLE SIDE	DOUBLE SIDE	SINGLE SIDE	DOUBLE SIDE		
180°	0.016	0.016	0.011	0.011	T <sub>J</sub> = T <sub>J</sub> maximum	K/W
120°	0.019	0.019	0.019	0.019		
90°	0.024	0.024	0.026	0.026		
60°	0.035	0.035	0.036	0.037		
30°	0.060	0.060	0.060	0.061		

**Note**

- The table above shows the increment of thermal resistance  $R_{thJC}$  when devices operate at different conduction angles than DC

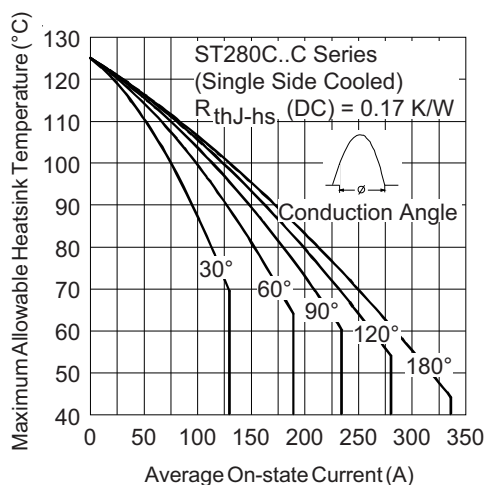


Fig. 1 - Current Ratings Characteristics

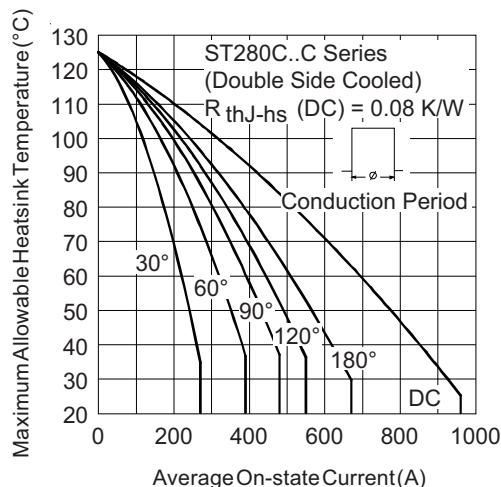


Fig. 4 - Current Ratings Characteristics

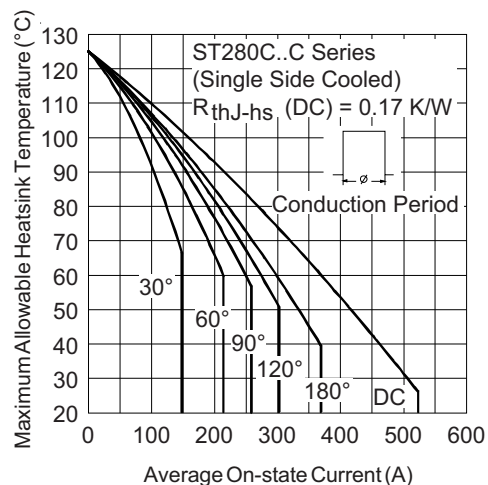


Fig. 2 - Current Ratings Characteristics

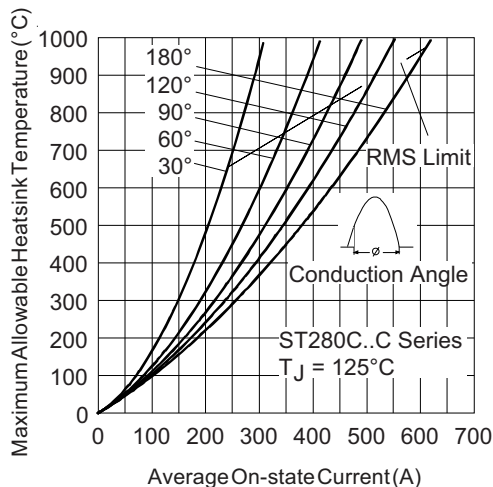


Fig. 5 - On-State Power Loss Characteristics

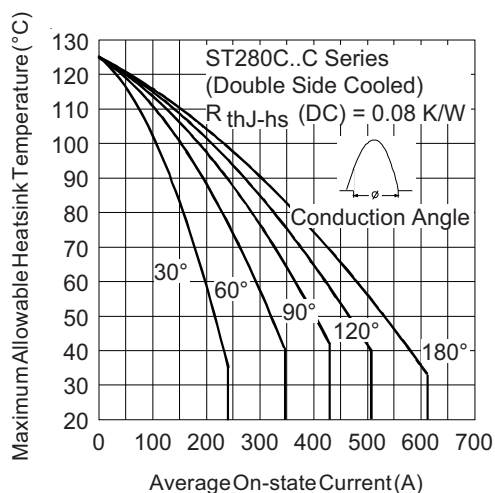


Fig. 3 - Current Ratings Characteristics

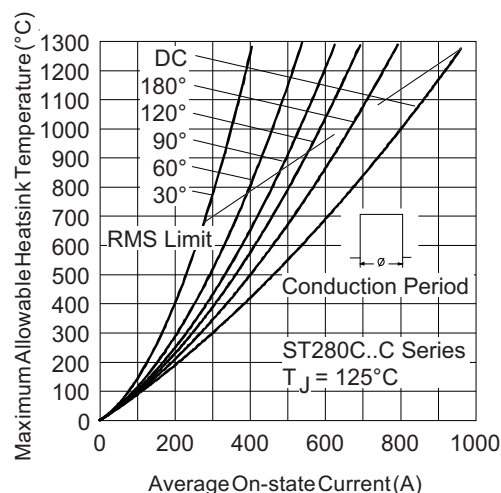


Fig. 6 - On-State Power Loss Characteristics

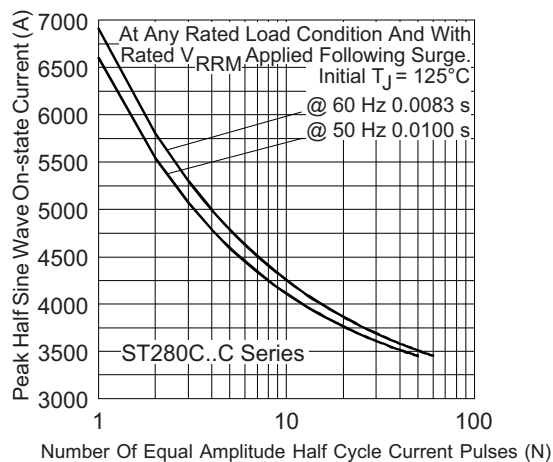


Fig. 7 - Maximum Non-Repetitive Surge Current Single and Double Side Cooled

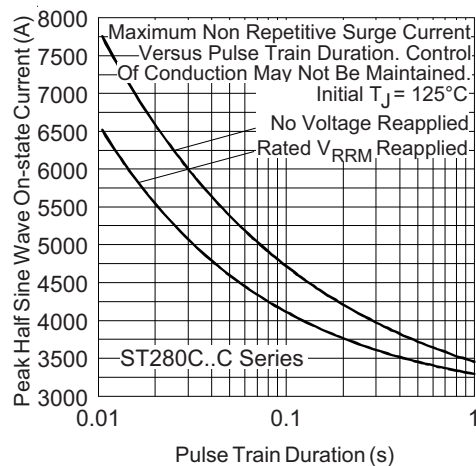


Fig. 8 - Maximum Non-Repetitive Surge Current Single and Double Side Cooled

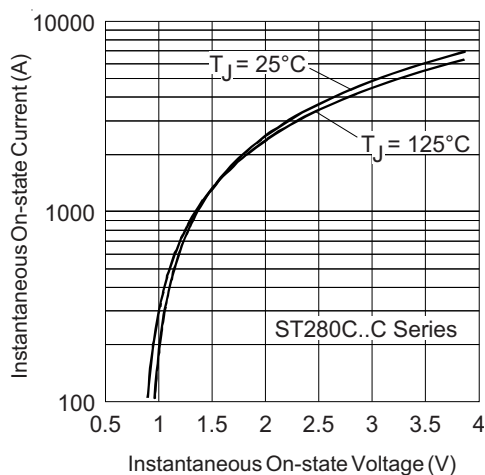
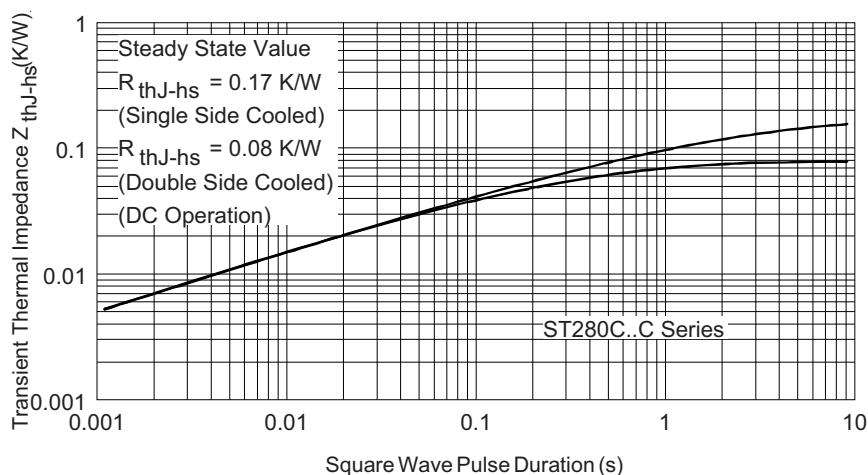


Fig. 9 - On-State Voltage Drop Characteristics

Fig. 10 - Thermal Impedance  $Z_{thJ-hs}$  Characteristics

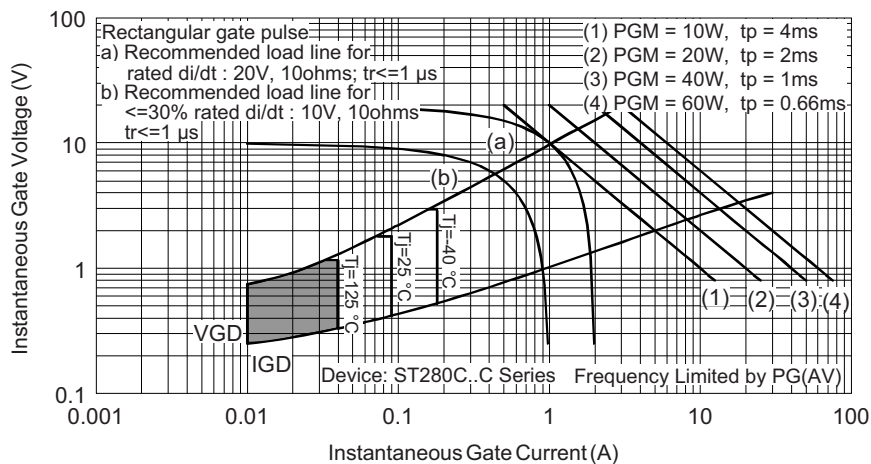


Fig. 11 - Gate Characteristics

## ORDERING INFORMATION TABLE

Device code	VS-	ST	28	0	C	06	C	1	-
	(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)
<b>1</b>	Vishay Semiconductors product								
<b>2</b>	Thyristor								
<b>3</b>	Essential part number								
<b>4</b>	0 = converter grade								
<b>5</b>	C = ceramic PUK								
<b>6</b>	Voltage code: code x 100 = $V_{RRM}$ (see Voltage Ratings table)								
<b>7</b>	C = PUK case A-PUK (TO-200AB)								
<b>8</b>	0 = eyelet terminals (gate and auxiliary cathode unsoldered leads) 1 = fast-on terminals (gate and auxiliary cathode unsoldered leads) 2 = eyelet terminals (gate and auxiliary cathode soldered leads) 3 = fast-on terminals (gate and auxiliary cathode soldered leads)								
<b>9</b>	Critical $dV/dt$ : • None = 500 V/ $\mu s$ (standard selection) • L = 1000 V/ $\mu s$ (special selection)								

## LINKS TO RELATED DOCUMENTS

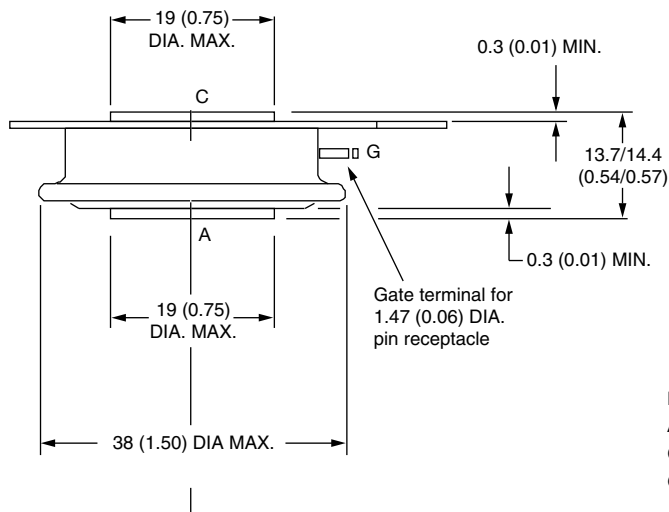
Dimensions

[www.vishay.com/doc?95074](http://www.vishay.com/doc?95074)

## A-PUK (TO-200AB)

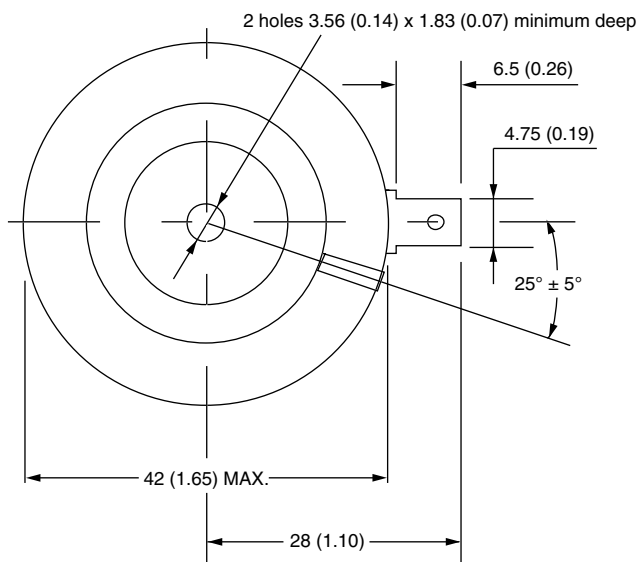
### DIMENSIONS in millimeters (inches)

Anode to gate  
Creepage distance: 7.62 (0.30) minimum  
Strike distance: 7.12 (0.28) minimum



#### Note:

A = Anode  
C = Cathode  
G = Gate



Quote between upper and lower pole pieces has to be considered after application of mounting force (see thermal and mechanical specification)



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